METHOD AND APPARATUS FOR SINGULATED DIE TESTING

Abstract

In accordance with one embodiment of the invention, a method of singulated die testing can be implemented. This can be implemented by obtaining a wafer and singulating the dies into individual die pieces. The singulated dies can be arranged in a separated testing arrangement and can even combine dies from multiple wafers as part of the combined arrangement. Then, testing can be implemented on the combined test arrangement.

Fig. 1